


**RECOMMENDED PCB LAYOUT**

**Note:**

1. Material:
  - 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
  - 1.2 Contact: copper alloy, t=0.20mm
  - 1.3 Shell: copper alloy, t=0.25mm
2. Specification:
  - 2.1 Current rating: 1 A Max.
  - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
  - 2.3 Contact resistance: 50 mW Max.
  - 2.4 Insulation resistance: 100 MW Min.
  - 2.5 Total mating force: 3.57 Kgf Max.
  - 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 3000 insertion/extraction cycles
  - 2.7 Temperature range: -30. C~80. C

<b>RoHS Compliant</b>		<b>HSM 玄茂科技股份有限公司</b> <b>HSUAN MAO TECHNOLOGY CO., LTD.</b>	
APPD. 核准		<b>TOLERANCE</b> 容許公差	<b>PART NAME</b> 品名
DWG. 製圖	<i>Helen</i>	SCALE 比例	MICRO USB AB TYPE 5PIN FEMALE STRAIGHT TYPE PIN:DIP TYPE & SHELL FOOT:DIP TYPE BLACK COLOR ROHS
DATE 制表日	2018/5/29	UNIT 單位	<b>PART NO.</b>
		PAGE 張數	料號
		1 OF 1	C8362-05ZBXX0R